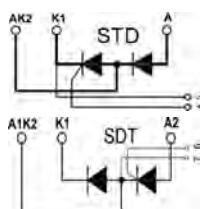


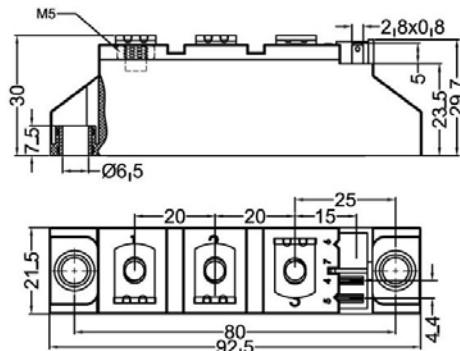
# STD100GKXX

## Thyristor-Diode Modules



Type	V <sub>RSM</sub> V <sub>D<sub>SM</sub></sub> V	V <sub>RRM</sub> V <sub>D<sub>RM</sub></sub> V
STD100GK08	900	800
STD100GK12	1300	1200
STD100GK14	1500	1400
STD100GK16	1700	1600
STD100GK18	1900	1800
STD100GK20	2100	2000
STD100GK22	2300	2200

Dimensions in mm (1mm=0.0394")



Symbol	Test Conditions	Maximum Ratings	Unit	
I <sub>TRMS</sub> , I <sub>FRMS</sub> I <sub>TAVM</sub> , I <sub>FAVM</sub>	T <sub>VJ</sub> =T <sub>VJM</sub> T <sub>C</sub> =85°C; 180° sine	180 100	A	
I <sub>TSM</sub> , I <sub>FSM</sub>	T <sub>VJ</sub> =45°C V <sub>R</sub> =0 T <sub>VJ</sub> =T <sub>VJM</sub> V <sub>R</sub> =0	1700 1800 1540 1640	A	
∫i <sup>2</sup> dt	T <sub>VJ</sub> =45°C V <sub>R</sub> =0 t=10ms (50Hz), sine t=8.3ms (60Hz), sine T <sub>VJ</sub> =T <sub>VJM</sub> V <sub>R</sub> =0 t=10ms(50Hz), sine t=8.3ms(60Hz), sine	14450 13500 11850 11300	A <sup>2</sup> s	
(di/dt) <sub>cr</sub>	T <sub>VJ</sub> =T <sub>VJM</sub> f=50Hz, t <sub>p</sub> =200us V <sub>D</sub> =2/3V <sub>DRM</sub> I <sub>G</sub> =0.45A dI <sub>G</sub> /dt=0.45A/us	repetitive, I <sub>T</sub> =250A non repetitive, I <sub>T</sub> =I <sub>TAVM</sub>	150 500	A/us
(dv/dt) <sub>cr</sub>	T <sub>VJ</sub> =T <sub>VJM</sub> ; V <sub>DR</sub> =2/3V <sub>DRM</sub> R <sub>GK</sub> =∞; method 1 (linear voltage rise)	1000	V/us	
P <sub>GM</sub>	T <sub>VJ</sub> =T <sub>VJM</sub> I <sub>T</sub> =I <sub>TAVM</sub>	t <sub>p</sub> =30us t <sub>p</sub> =300us	10 5	W
P <sub>GAV</sub>			0.5	W
V <sub>RGM</sub>			10	V
T <sub>VJ</sub> T <sub>VJM</sub> T <sub>stg</sub>		-40...+125 125 -40...+125	°C	
V <sub>ISOL</sub>	50/60Hz, RMS I <sub>ISOL</sub> ≤1mA	t=1min t=1s	3000 3600	V~
M <sub>d</sub>	Mounting torque (M5) Terminal connection torque (M5)	2.5-4.0/22-35 2.5-4.0/22-35	Nm/lb.in.	
Weight	Typical	78	g	

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# STD100GKXX

## Thyristor-Diode Modules

Symbol	Test Conditions	Characteristic Values	Unit
$I_{RRM}, I_{DRM}$	$T_{VJ}=T_{VJM}; V_R=V_{RRM}; V_D=V_{DRM}$	15	mA
$V_T, V_F$	$I_T, I_F=300A; T_{VJ}=25^\circ C$	1.74	V
$V_{TO}$	For power-loss calculations only ( $T_{VJ}=T_{VJM}$ )	0.85	V
$r_T$		3.2	$m\Omega$
$V_{GT}$	$V_D=6V; T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	1.5 1.6	V
$I_{GT}$	$V_D=6V; T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	100 200	mA
$V_{GD}$	$T_{VJ}=T_{VJM}; V_D=2/3V_{DRM}$	0.25	V
$I_{GD}$	$T_{VJ}=T_{VJM}; V_D=2/3V_{DRM}$	10	mA
$I_L$	$T_{VJ}=25^\circ C; t_p=30\mu s; V_D=6V$ $I_G=0.45A; dI/dt=0.45A/\mu s$	200	mA
$I_H$	$T_{VJ}=25^\circ C; V_D=6V; R_{GK}=\infty$	150	mA
$t_{gd}$	$T_{VJ}=25^\circ C; V_D=1/2V_{DRM}$ $I_G=0.45A; dI/dt=0.45A/\mu s$	2	us
$t_q$	$T_{VJ}=T_{VJM}; I_T=150A; t_p=200\mu s; -dI/dt=10A/\mu s$ $V_R=100V; dv/dt=20V/\mu s; V_D=2/3V_{DRM}$	typ. 185	us
$Q_s$	$T_{VJ}=T_{VJM}; I_T, I_F=50A; -dI/dt=6A/\mu s$	170	uC
$I_{RM}$		45	A
$R_{thJC}$	per thyristor/diode; DC current per module	0.22 0.11	K/W
$R_{thJK}$	per thyristor/diode; DC current per module	0.42 0.21	K/W
$ds$	Creeping distance on surface	12.7	mm
$da$	Creepage distance in air	9.6	mm
$a$	Maximum allowable acceleration	50	$m/s^2$

### FEATURES

- \* International standard package
- \* DCB base plate
- \* Glass passivated chips
- \* Isolation voltage 3600 V~
- \* UL File NO.E310749
- \* RoHS compliant

### APPLICATIONS

- \* DC motor control
- \* Softstart AC motor controller
- \* Light, heat and temperature control

### ADVANTAGES

- \* Space and weight savings
- \* Simple mounting with two screws
- \* Improved temperature and power cycling
- \* Reduced protection circuits

# STD100GKXX

## Thyristor-Diode Modules

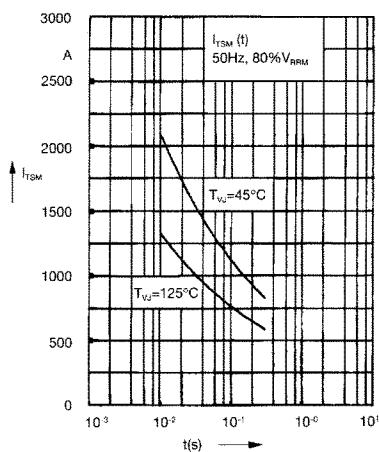


Fig. 1 Surge overload current  
 $I_{TSM}, I_{FSM}$ : Crest value,  $t$ : duration

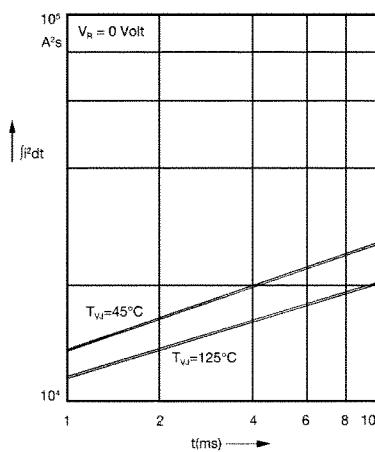


Fig. 2  $\int I^2 dt$  versus time (1-10 ms)

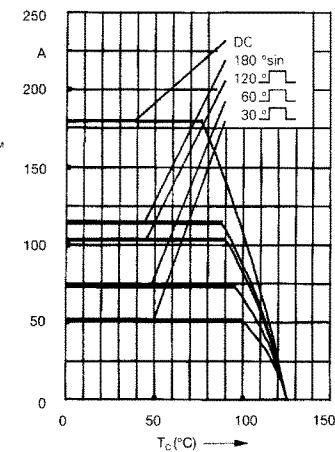


Fig. 2a Maximum forward current  
at case temperature

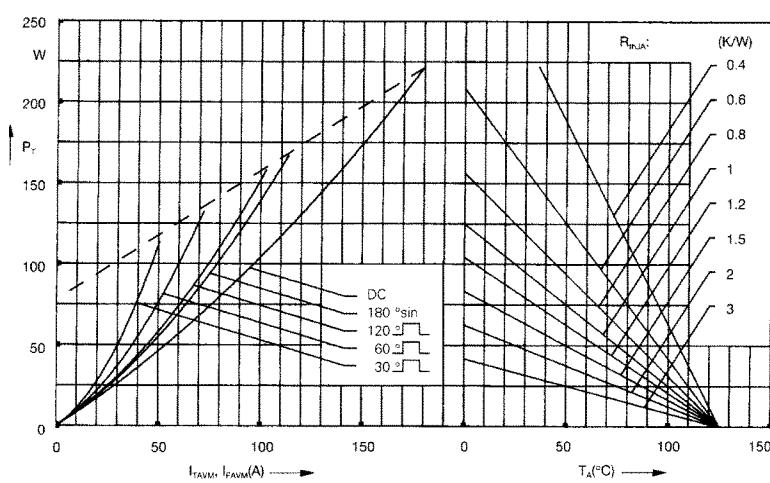


Fig. 3 Power dissipation versus on-state current and ambient temperature  
(per thyristor or diode)

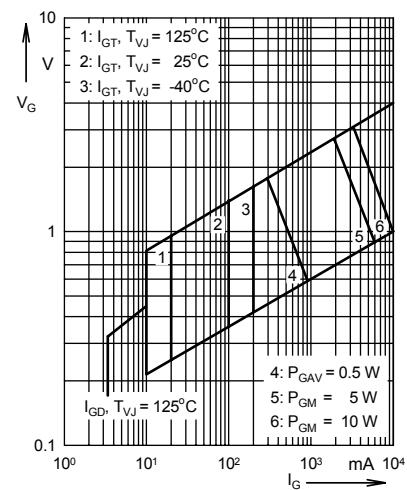


Fig. 4 Gate trigger characteristics

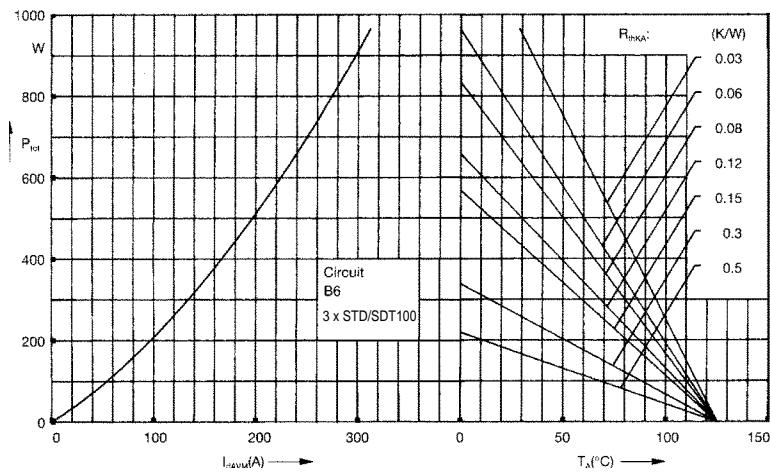


Fig. 5 Three phase rectifier bridge: Power dissipation versus direct output current  
and ambient temperature

3 x STD/SDT100

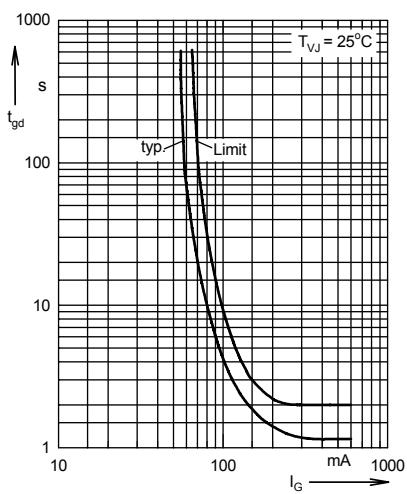


Fig. 6 Gate trigger delay time

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## Thyristor-Diode Modules

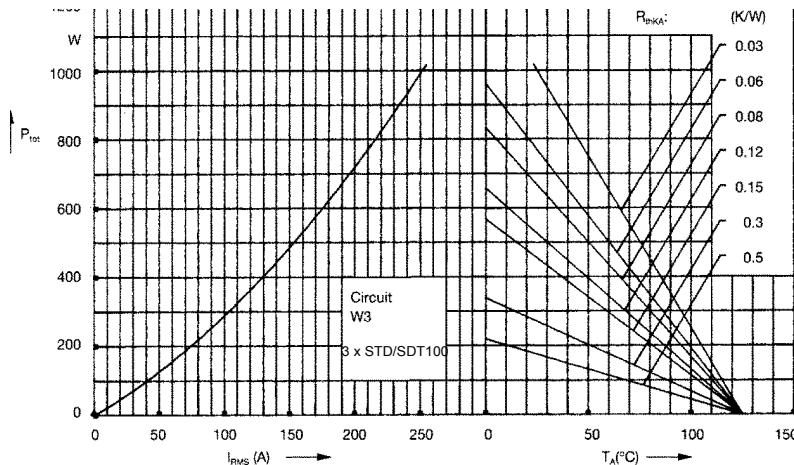


Fig. 7 Three phase AC-controller:  
Power dissipation versus RMS  
output current and ambient  
temperature

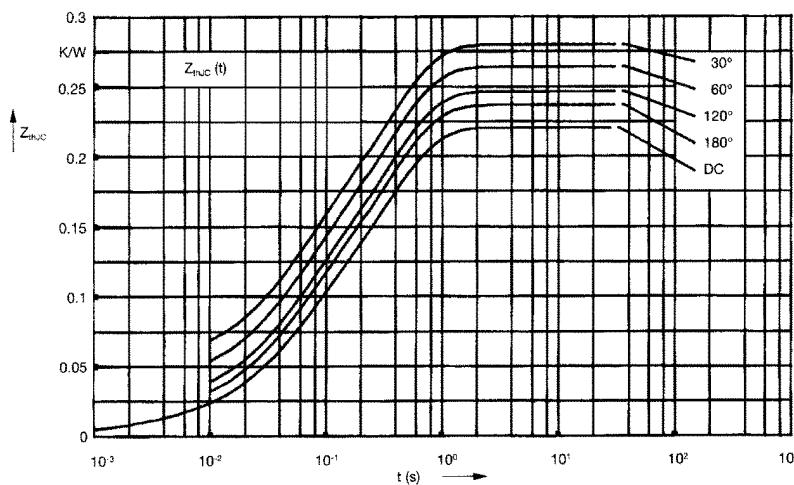


Fig. 8 Transient thermal impedance  
junction to case (per thyristor or  
diode)

$R_{thJC}$  for various conduction angles d:

d	$R_{thJC}$ (K/W)
DC	0.22
180°	0.23
120°	0.25
60°	0.27
30°	0.28

Constants for  $Z_{thJC}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.0066	0.0019
2	0.0678	0.0477
3	0.1456	0.344

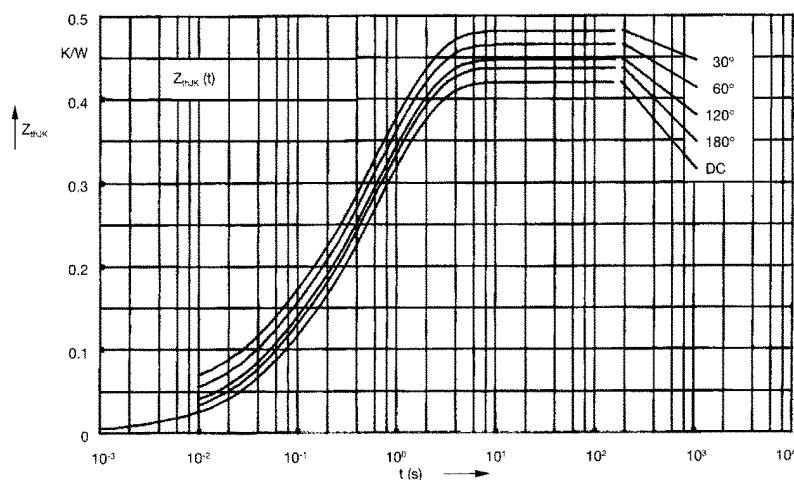


Fig. 9 Transient thermal impedance  
junction to heatsink (per thyristor  
or diode)

$R_{thJK}$  for various conduction angles d:

d	$R_{thJK}$ (K/W)
DC	0.42
180°	0.43
120°	0.45
60°	0.47
30°	0.48

Constants for  $Z_{thJK}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.0066	0.0019
2	0.0678	0.0477
3	0.1456	0.344
4	0.2	1.32

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